

Following authors have been selected to receive the CPMT Travel Award for the 60th ECTC:

Abstract	Title	First	Last	email
508	Thermal cycle and drop reliability of Pb-free assemblies	Bankeem	Chheda	bankeemchheda@gmail.com
545	High Speed Touch Screen Assembly using	Seung-Ho	Kim	kwpaik@kaist.ac.kr
660	Micro/Nano Structure Size Effect on Superhydrophobicity	Yan	Liu	cp.wong@mse.gatech.edu
448	Effect of Ultrasonic Energy on Interfacial Structure and Bond	Hui	Xu	H.Xu3@lboro.ac.uk
270	Near-Eutectic Sn-Ag-Cu Solder Bumps Formation for Flip-Chip	Yi	Qin	Y.Qin@lboro.ac.uk
470	High Power and Fine Pitch Assembly Method	Kiwon	Lee	kwpaik@kaist.ac.kr
599	Terahertz packaging: study of substrates	Jose	Hejase	hejasejo@msu.edu